

ABSTRACT OF THE DISCLOSURE

A functional PCB module in accordance with the present invention comprises a frame having at least one chip recess, at least one chip mounted in the chip recess, at least one printed circuit formed on one side of the frame and material filling the chip recess. The chip has terminals interconnected to the printed circuit. Since the chip is embedded in the frame to complete the functional PCB module, the functional PCB module is effectively thinner. Furthermore, two or more functional PCB modules are easily combined to form a multi-layer PCB by using a vacuum compression process.